

March 1988 Revised August 1999

74F646 • 74F646B • 74F648 Octal Transceiver/Register with 3-STATE Outputs

General Description

These devices consist of bus transceiver circuits with 3-STATE, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus will be clocked into the registers as the appropriate clock pin goes to a high logic level. Control \overline{G} and direction pins are provided to control the transceiver function. In the transceiver mode, data present at the high impedance port may be stored in either the A or the B register or in both. The select controls can multiplex stored and real-time (transparent mode) data. The direction control determines which bus will receive data when the enable control \overline{G} is Active LOW. In the isolation mode (control \overline{G} HIGH), A data may be stored in the B register and/or B data may be stored in the A register.

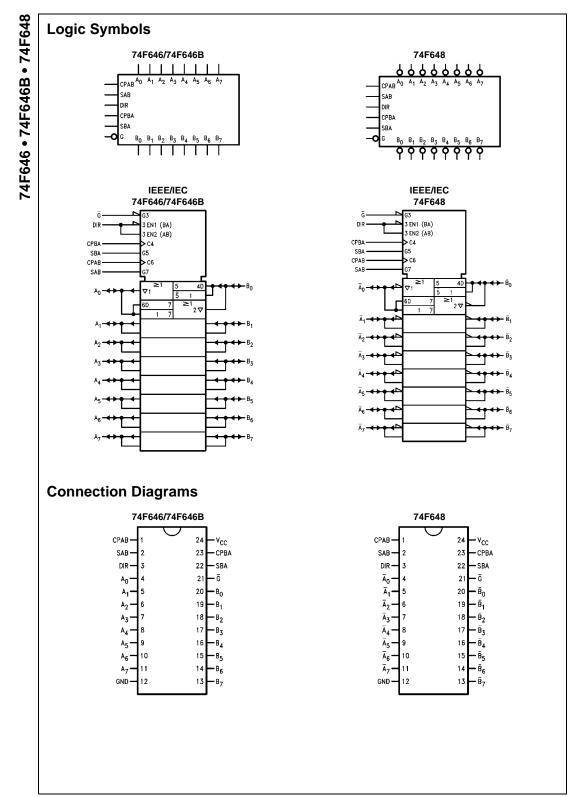
Features

- Independent registers for A and B buses
- Multiplexed real-time and stored data
- 74F648 has inverting data paths
- 74F646/74F646B have non-inverting data paths
- 74F646B is a faster version of the 74F646
- 3-STATE outputs
- 300 mil slim DIP

Ordering Code:

Order Number	Package Number	Package Description
74F646SC	M24B	24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F646MSA	MSA24	24-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74F646SPC	N24C	24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-100, 0.300 Wide
74F646BSC	M24B	24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F646BSPC	N24C	24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-100, 0.300 Wide
74F648SC	M24B	24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F648SPC	N24C	24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-100, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.



Unit Loading/Fan Out

Pin Names	Docarintian	U.L.	Input I _{IH} /I _{IL}
riii Nailles	Description	HIGH/LOW	Output I _{OH} /I _{OL}
A ₀ -A ₇	Data Register A Inputs/	3.5/1.083	70 μΑ/–650 μΑ
	3-STATE Outputs	600/106.6 (80)	-12 mA/64 mA (48 mA)
B ₀ -B ₇	Data Register B Inputs/	3.5/1.083	70 μΑ/–650 μΑ
	3-STATE Outputs	600/106.6 (80)	-12 mA/64 mA (48 mA)
СРАВ, СРВА	Clock Pulse Inputs	1.0/1.0	20 μA/–0.6 mA
SAB, SBA	Select Inputs	1.0/1.0	20 μA/–0.6 mA
G	Output Enable Input	1.0/1.0	20 μA/–0.6 mA
DIR	Direction Control Input	1.0/1.0	$20~\mu\text{A}/\!\!-\!0.6~\text{mA}$

Function Table

		Inp	uts			Data I/O	(Note 1)	5
G	DIR	СРАВ	СРВА	SAB	SBA	A ₀ -A ₇	B ₀ -B ₇	Function
Н	Χ	H or L	H or L	Χ	Χ			Isolation
Н	Χ	~	X	Χ	X	Input	Input	Clock A _n Data into A Register
Н	Χ	Χ	~	Χ	Χ			Clock B _n Data into B Register
L	Н	Х	X	L	Χ			A _n to B _n —Real Time (Transparent Mode)
L	Н	~	X	L	X	Input	Output	Clock A _n Data into A Register
L	Н	H or L	X	Н	Χ			A Register to B _n (Stored Mode)
L	Н	~	Χ	Н	Χ			Clock A _n Data into A Register and Output to B _n
L	L	Х	Х	Χ	L			B _n to A _n —Real Time (Transparent Mode)
L	L	X	~	Χ	L	Output	Input	Clock B _n Data into B Register
L	L	X	H or L	Χ	Н			B Register to A _n (Stored Mode)
L	L	X	~	Χ	Н			Clock B _n Data into B Register and Output to A _n

H = HIGH Voltage Level

Note 1: The data output functions may be enabled or disabled by various signals at the G and DIR Inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every LOW-to-HIGH transition of the clock inputs.

L = LOW Voltage Level X = Irrelevant

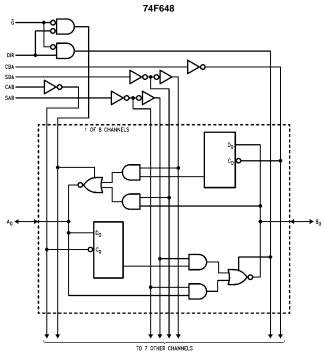
⁼ LOW-to-HIGH Transition

Logic Diagrams

74F646/74F646B GRACH CIRAL SIBA CAR CAR TO THE CHANNELS TO 7 OTHER CHANNELS

TO 7 OTHER CHANNELS

Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.



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Absolute Maximum Ratings(Note 2)

 $\begin{array}{ll} \mbox{Storage Temperature} & -65\mbox{°C to } +150\mbox{°C} \\ \mbox{Ambient Temperature under Bias} & -55\mbox{°C to } +125\mbox{°C} \\ \end{array}$

 $\begin{array}{lll} \mbox{Junction Temperature under Bias} & -55^{\circ}\mbox{C to } +150^{\circ}\mbox{C} \\ \mbox{V}_{\mbox{CC}} \mbox{ Pin Potential to Ground Pin} & -0.5\mbox{V to } +7.0\mbox{V} \end{array}$

Input Voltage (Note 3) -0.5V to +7.0V Input Current (Note 3) -30 mA to +5.0 mA

Voltage Applied to Output in HIGH State (with $V_{CC} = 0V$)

 $\begin{array}{ll} \text{Standard Output} & -0.5 \text{V to V}_{\text{CC}} \\ \text{3-STATE Output} & -0.5 \text{V to +5.5V} \end{array}$

Current Applied to Output

Recommended Operating Conditions

Free Air Ambient Temperature 0°C to +70°C Supply Voltage +4.5V to +5.5V

Note 2: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 3: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter	Min	Тур	Max	Units	v _{cc}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			8.0	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA (Non I/O Pins)
V _{OH}	Output HIGH 10% V Voltage	CC 2.0			V	Min	$I_{OH} = -15 \text{ mA } (A_n, B_n)$
V _{OL}	Output LOW 10% V Voltage	cc		0.55	V	Min	I _{OL} = 64 mA (A _n , B _n)
I _{IH}	Input HIGH Current			5.0	μА	Max	V _{IN} = 2.7V (Non I/O Pins)
I _{BVI}	Input HIGH Current Breakdown Test			7.0	μА	Max	V _{IN} = 7.0V (Non I/O Pins)
I _{BVIT}	Input HIGH Current Breakdown (I/O)			0.5	mA	Max	$V_{IN} = 5.5V (A_n, B_n)$
I _{CEX}	Output HIGH Leakage Current			50	μА	Max	V _{OUT} = V _{CC}
V_{ID}	Input Leakage Test	4.75			V	0.0	$I_{ID} = 1.9 \mu A$ All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current			3.75	μА	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			-0.6	mA	Max	V _{IN} = 0.5V (Non I/O Pins)
I _{IH} + I _{OZH}	Output Leakage Current			70	μΑ	Max	$V_{OUT} = 2.7V (A_n, B_n)$
I _{IL} + I _{OZL}	Output Leakage Current			-650	μΑ	Max	$V_{OUT} = 0.5V (A_n, B_n)$
los	Output Short-Circuit Current	-100		-225	mA	Max	V _{OUT} = 0V
I _{ZZ}	Bus Drainage Test			500	μΑ	0.0V	V _{OUT} = 5.25V
I _{CCH}	Power Supply Current			135	mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current			150	mA	Max	$V_O = LOW$
I _{CCZ}	Power Supply Current			150	mA	Max	V _O = HIGH Z

AC Electrical Characteristics 74F646/74F648

		$T_A =$	+25°C	$T_A = -55^{\circ}C$	C to +125°C	$T_A = 0$ °C to +70°C		Units
Symbol	Parameter	V _{CC} =	+5.0V	V _{CC} =	+5.0V	$V_{CC} =$		
Symbol	Farameter	C _L =	50 pF	C _L =	50 pF	$C_L = 50 \ pF$		
		Min	Max	Min	Max	Min	Max	
f _{MAX}	Maximum Clock Frequency	90		75		90		MHz
t _{PLH}	Propagation Delay	2.0	7.0	2.0	8.5	2.0	8.0	ns
t _{PHL}	Clock to Bus	2.0	8.0	2.0	9.5	2.0	9.0	115
t _{PLH}	Propagation Delay	1.0	7.0	1.0	8.0	1.0	7.5	ns
t _{PHL}	Bus to Bus (74F646)	1.0	6.5	1.0	8.0	1.0	7.0	115
t _{PLH}	Propagation Delay	2.0	8.5	1.0	10.0	2.0	9.0	ns
t _{PHL}	Bus to Bus (74F648)	1.0	7.5	1.0	9.0	1.0	8.0	115
t _{PLH}	Propagation Delay	2.0	8.5	2.0	11.0	2.0	9.5	ns
t _{PHL}	SBA or SAB to A or B	2.0	8.0	2.0	10.0	2.0	9.0	115
t _{PZH}	Enable Time	2.0	8.5	2.0	10.0	2.0	9.0	
t _{PZL}	OE to A or B	2.0	12.0	2.0	13.5	2.0	12.5	ns
t _{PHZ}	Disable Time	1.0	7.5	1.0	9.0	1.0	8.5	
t _{PLZ}	OE to A or B	2.0	9.0	2.0	11.0	2.0	9.5	ns
t _{PZH}	Enable Time	2.0	14.0	2.0	16.0	2.0	15.0	ns
t _{PZL}	DIR to A or B	2.0	13.0	2.0	15.0	2.0	14.0	115
t _{PHZ}	Disable Time	1.0	9.0	1.0	10.0	1.0	9.5	ns
t _{PLZ}	DIR to A or B	2.0	11.0	2.0	12.0	2.0	11.5	115

AC Operating Requirements 74F646/74F648

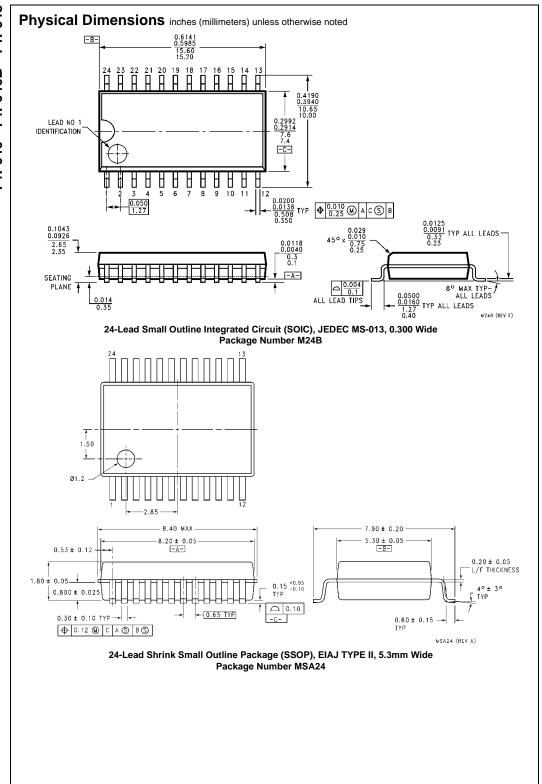
		$T_A = +25^{\circ}C$		T _A = -55°C	c to +125°C	T _A = 0°C to +70°C			
Symbol	Parameter	V _{CC} =	+5.0V	V _{CC} =	+5.0V	$V_{CC} = +5.0V$		Units	
		Min	Max	Min	Max	Min	Max		
t _S (H)	Setup Time, HIGH or LOW	5.0		5.0		5.0		ns	
t _S (L)	Bus to Clock	5.0		5.0		5.0			
t _H (H)	Hold Time, HIGH or LOW	2.0		2.5		2.0		ns	
t _H (L)	Bus to Clock	2.0		2.5		2.0		115	
t _W (H)	Clock Pulse Width	5.0		5.0		5.0		ns	
t _W (L)	HIGH or LOW	5.0		5.0		5.0		115	

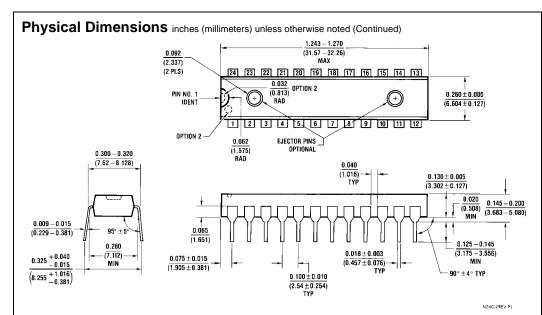
AC Electrical Characteristics 74F646B

		T _A = +25°C		$T_A = -55^{\circ}C$	C to +125°C	$T_A = 0$ °C to +70°C		
Symbol	Parameter	V _{CC} =	+5.0V	V _{CC} =	+5.0V	V _{CC} =	Units	
Зупівої		$C_L =$	50 pF	C _L =	50 pF	C _L = 50 pF		
		Min	Max	Min	Max	Min	Max	1
f _{MAX}	Maximum Clock Frequency	165				150		MHz
t _{PLH}	Propagation Delay	2.5	7.0			2.5	8.0	ns
t _{PHL}	Clock to Bus	3.0	7.5			3.0	8.0	115
t _{PLH}	Propagation Delay	2.0	6.0			2.0	7.0	ns
t _{PHL}	Bus to Bus	2.0	6.0			2.0	7.0	113
t _{PLH}	Propagation Delay	2.5	7.5			2.5	8.5	ns
t _{PHL}	SBA or SAB to A or B	2.5	7.5			2.5	8.5	115
t _{PZH}	Enable Time	2.5	6.5			2.5	8.0	
t _{PZL}	OE to A or B	2.5	9.0			2.5	10.0	ns
t _{PHZ}	Disable Time	1.5	6.5			1.5	7.5	
t_{PLZ}	OE to A or B	2.0	7.0			2.0	8.5	ns
t _{PZH}	Enable Time	2.0	7.0			2.0	8.5	ns
t _{PZL}	DIR to A or B	3.0	9.5			3.0	10.0	115
t _{PHZ}	Disable Time	1.5	7.5			1.5	8.5	ns
t _{PLZ}	DIR to A or B	2.5	8.5			2.5	9.5	IIS

AC Operating Requirements 74F646B

Symbol	Parameter	$T_A = +25^{\circ}C$ $V_{CC} = +5.0V$		**	to +125°C +5.0V	$T_A = 0$ °C to +70°C $V_{CC} = +5.0V$		Units	
G y26.	i diamoto.	Min	Max	Min	Max	Min	Max		
t _S (H)	Setup Time, HIGH or LOW	5.0				4.0			
t _S (L)	Bus to Clock	5.0				4.0		ns	
t _H (H)	Hold Time, HIGH or LOW	1.5				1.5			
t _H (L)	Bus to Clock	1.5				1.5		ns	
t _W (H)	Clock Pulse Width	5.0				5.0		no	
t _W (L)	HIGH or LOW	5.0				5.0		ns	





24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-100, 0.300 Wide Package Number N24C

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